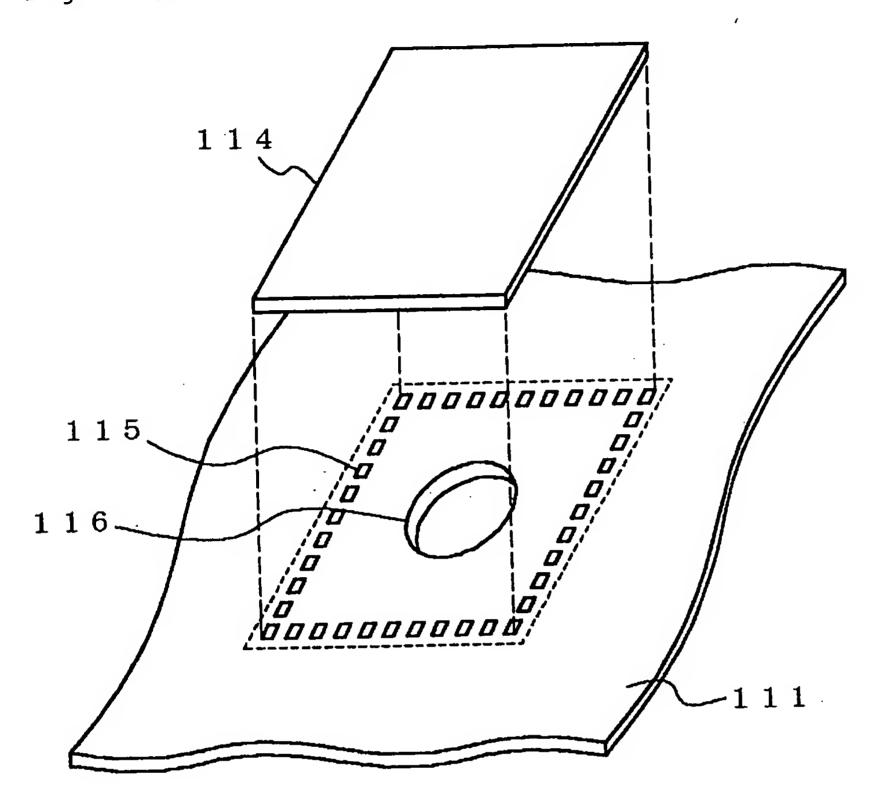
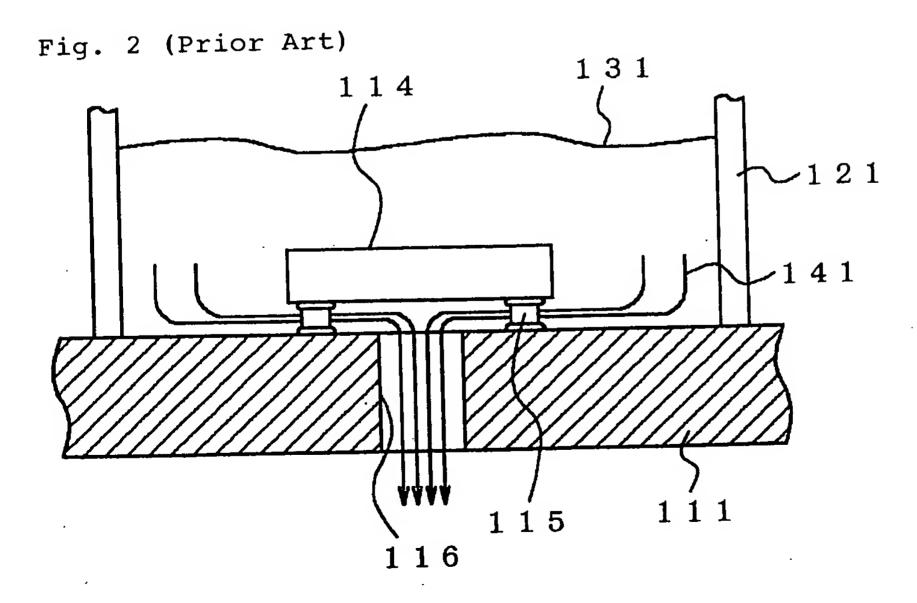
Motoaki MATSUDA
"Flip-Chip BGA Semiconductor Device for Achieving a Superior Cleaning Effect"
Q77402—Filed September 11, 2003
Sheets _____ of 6

Fig. 1 (Prior Art)





Motoaki MATSUDA "Flip-Chip BGA Semiconductor Device for Achieving a Superior Cleaning Effect" Q77402—Filed September 11, 2003 Sheets 2 of 6

Fig. 3a

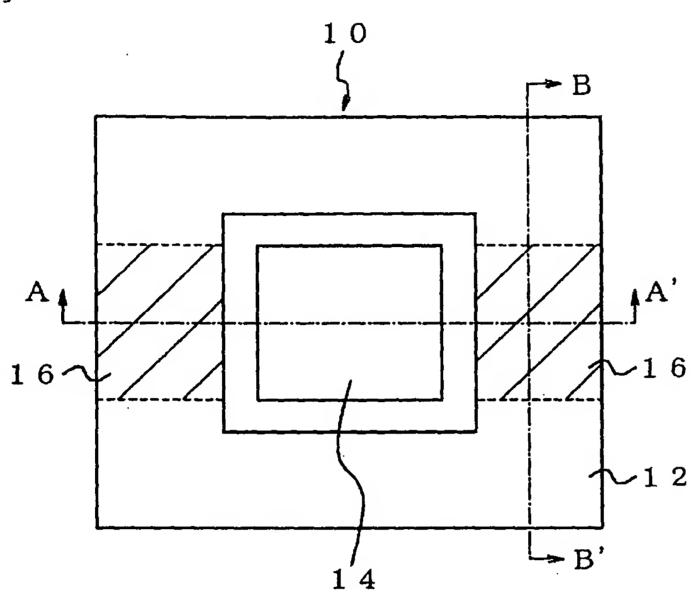


Fig. 3b

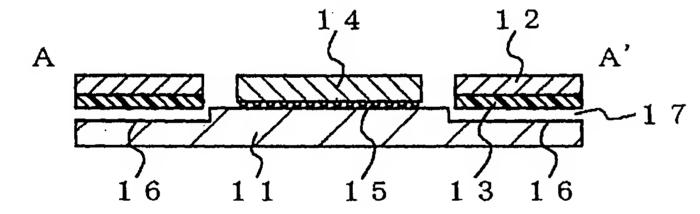
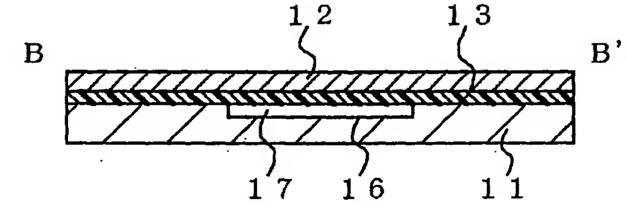
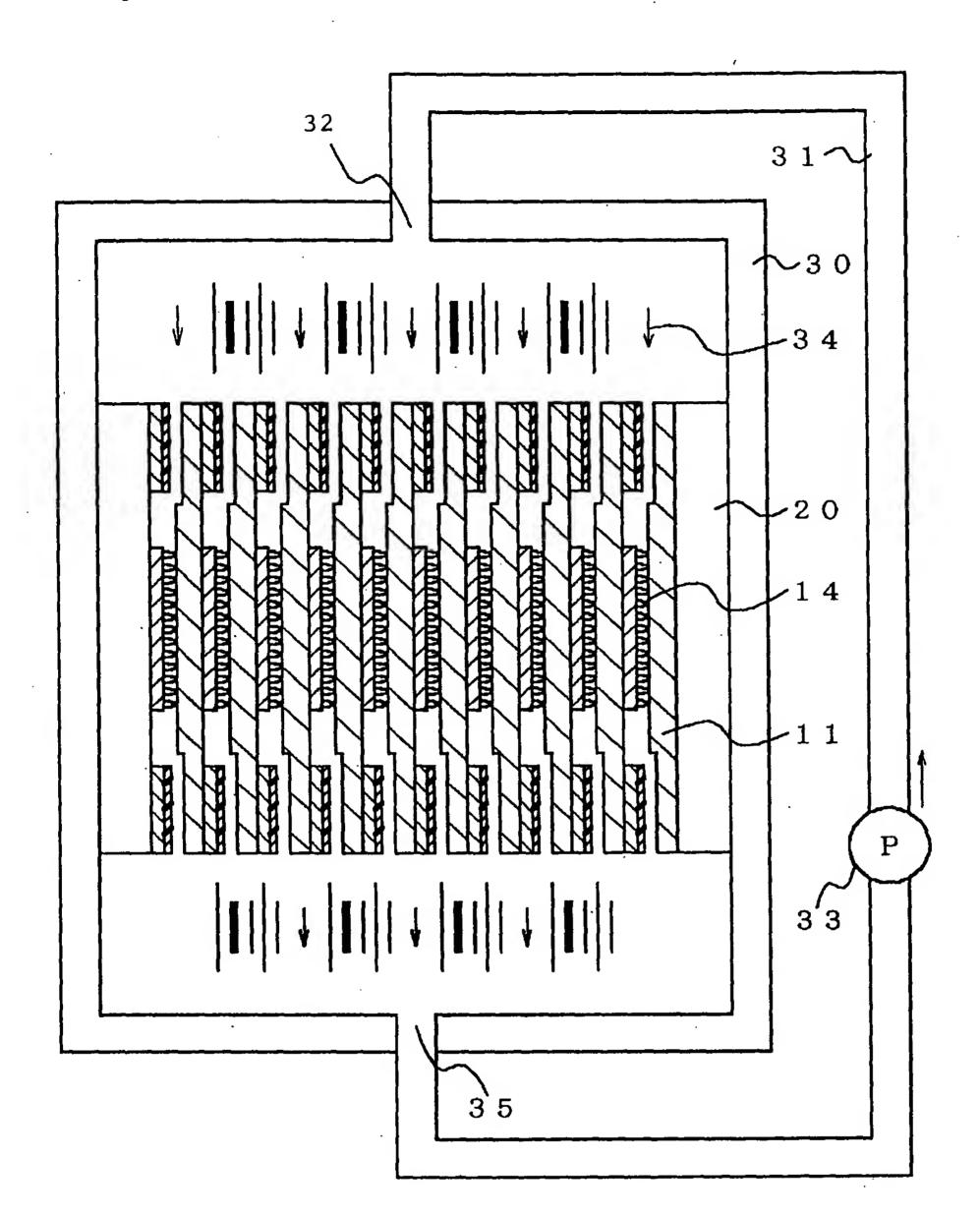


Fig. 3c



Motoaki MATSUDA
"Flip-Chip BGA Semiconductor Device for Achieving a Superior Cleaning Effect"
Q77402—Filed September 11, 2003
Sheets 3 of 6

Fig. 4



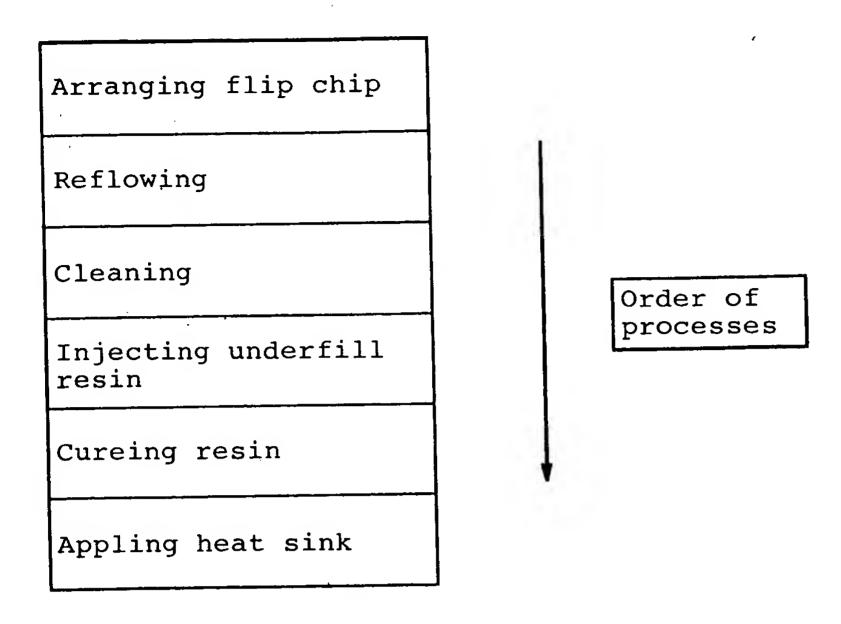
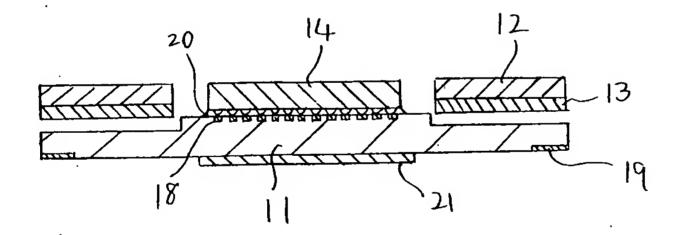


Fig. 6



Motoaki MATSUDA
"Flip-Chip BGA Semiconductor Device for Achieving a Superior Cleaning Effect"
Q77402—Filed September 11, 2003
Sheets 5 of 6

Fig. 7a

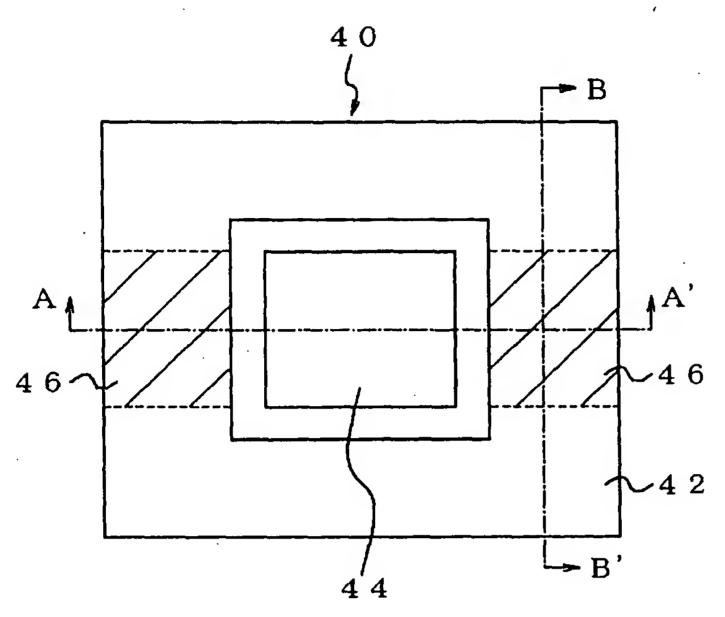


Fig. 7b

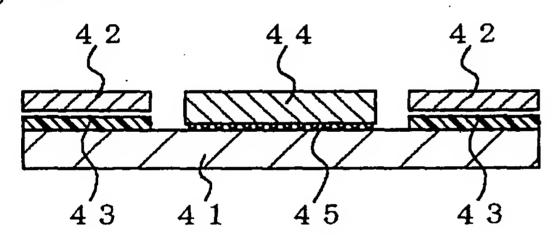
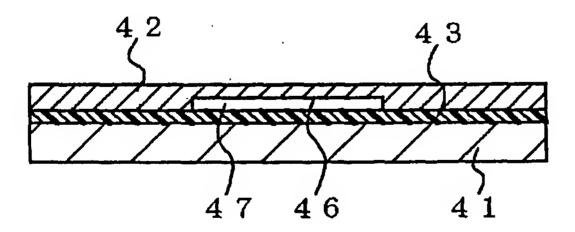


Fig. 7c



Motoaki MATSUDA "Flip-Chip BGA Semiconductor Device for Achieving a Superior Cleaning Effect" Q77402——Filed September 11, 2003 Sheets 6 of 6

Fig. 8a

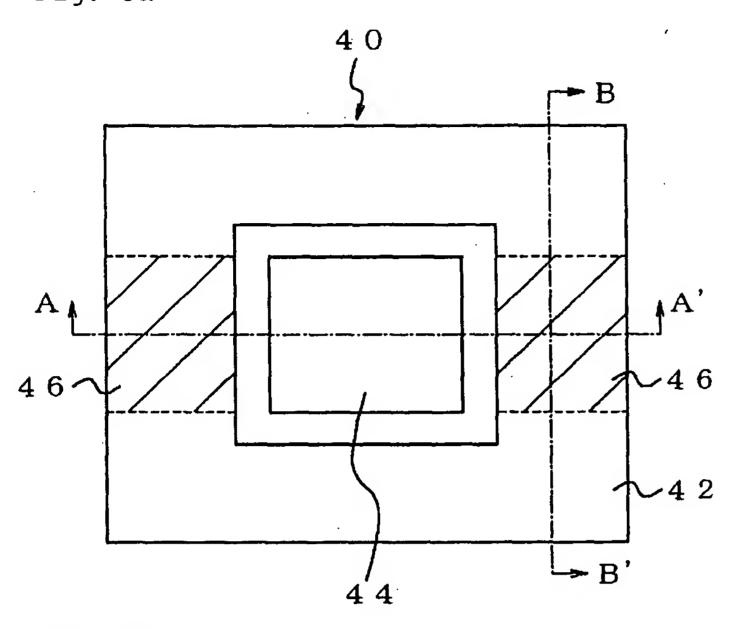


Fig. 8b

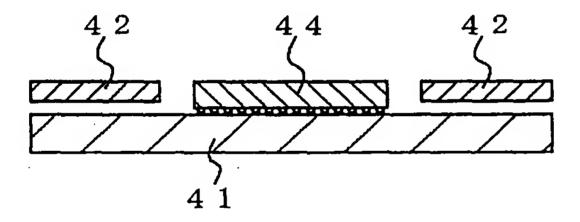


Fig. 8c

